

/ Descriptions

TO-3P

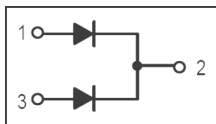
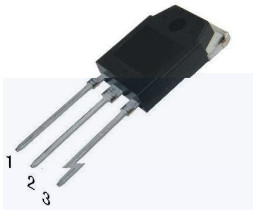
Ultrafast Recovery Diode in a TO-3P Plastic Package.

/ Features

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

/ Applications

For high frequency, high voltage, high current rectifier diode, freewheeling diode

/ Equivalent Circuit**/ Pinning**

PIN1 Anode PIN2 Cathode PIN 3 Anode

/ h_{FE} Classifications & Marking

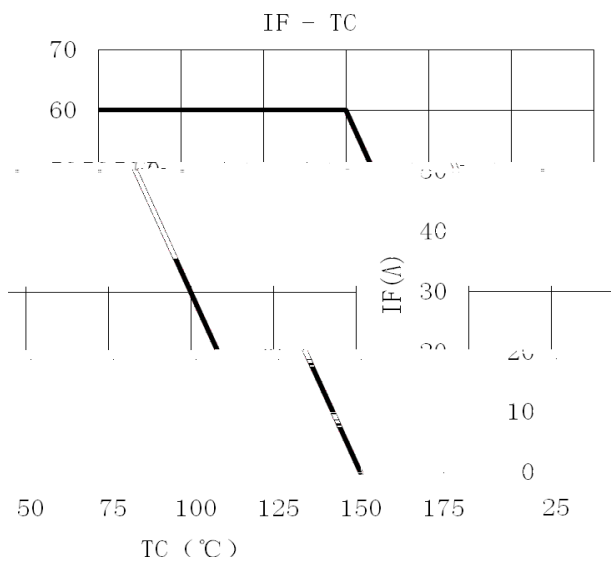
See Marking Instructions

MUR6060PT

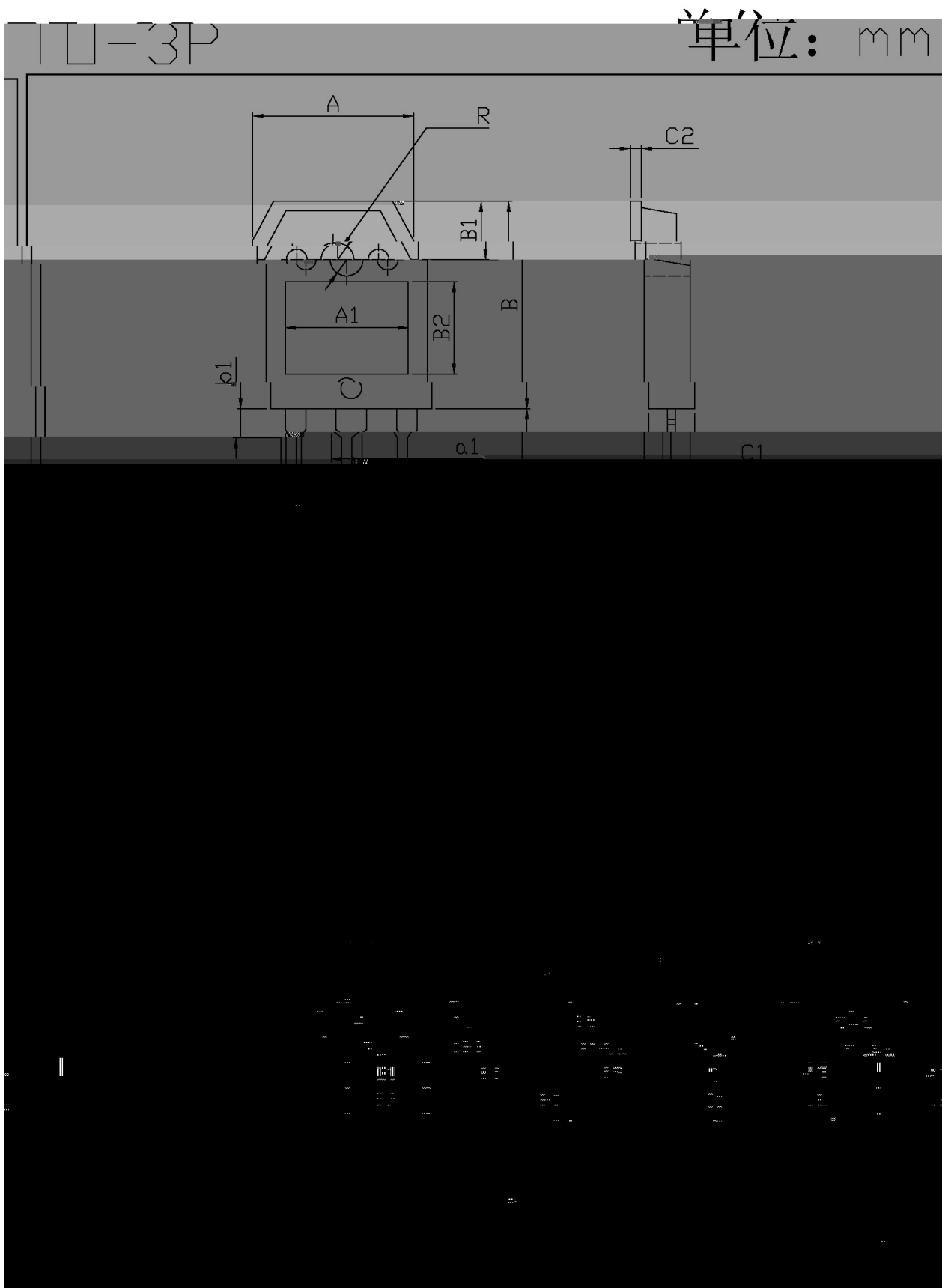
Rev.E Mar.-2016

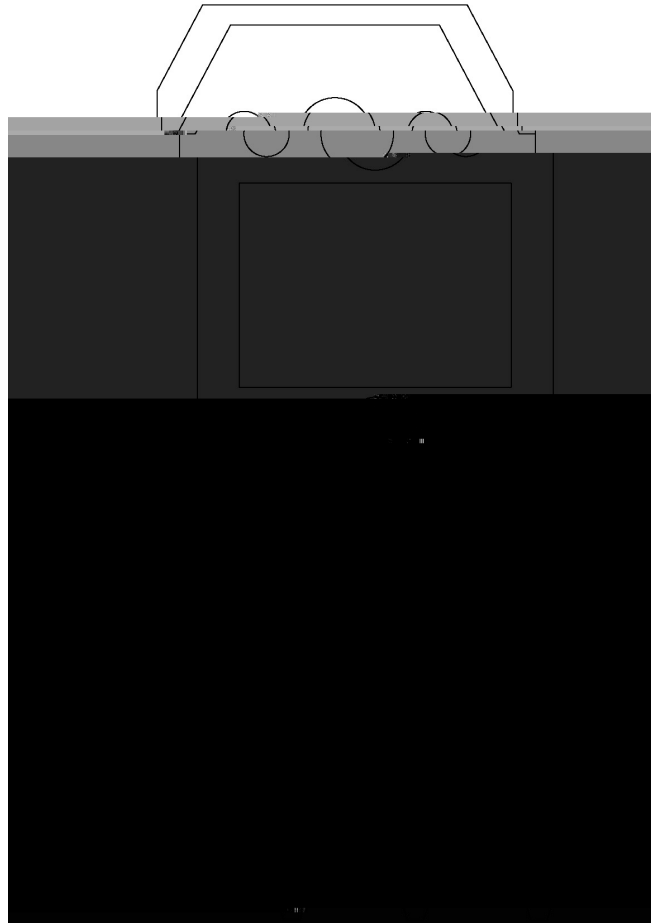
DATA SHEET

/ Electrical Characteristic Curve



/ Package Dimensions





() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. | |

/ Resistance to Soldering Heat Test Conditions

270±5	10±1 sec.	Temp.:270±5	Time:10±1 sec
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/ Packaging SPEC.

/ TUBE

Package Type	Units	Dimension	(unit mm ³)
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